



DEFENSE LOGISTICS AGENCY  
LAND AND MARITIME  
POST OFFICE BOX 3990  
COLUMBUS, OH 43218-3990

December 15, 2011

Mr. Kurt Moe  
Micom Circuits  
475 NW Eight Ave  
New Brighton MN 55112M

Dear Mr. Moe:

RE: Notification of Add-On Qualification, MIL-PRF-31032; FSC 5998; CAGE Code 34076;  
VQE-12-023661 / 034938

Qualification of additional capabilities is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032 and associated specifications MIL-PRF-31032/1 and MIL-PRF-31032/2 and in accordance with the TRB approved test plan. Conductive and non-conductive hole fill have been added to the GF and GI base material listings. The GF listing has been modified to include embedded resistors. The current Qualified Manufacturers List QML-31032 shall be updated to reflect the changes below.

MANUFACTURER	PLANT LOCATIONS	CAGE CODE: 34076
Micom Corporation 475 Old Highway 8 NW New Brighton, MN 55112	Same Address as Manufacturer	PHONE #: 651-604-2625 FAX #: 651-636-1352 EMAIL: kmoe@micomcircuits.com
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Qualification Letters: VQE-02-002780, VQE-03-002980, VQE-12-023661 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Max. Panel Size: 18" x 24" Max. Number of Layers: 28 Max. Board Thickness: .239" Min. Hole Size: .007" Drilled Plated-Through Hole Before Plating Aspect Ratio: 11:1 Through-Hole Min. Conductor Width/Space: .004 "/.004" Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback Hole Wall Conductive Coating: Electroless Copper Copper Plating: Direct Current Plate Hole Fill / Via Plug: <b>Conductive, Non-Conductive</b> Solder Resist: Dry Film, Liquid Photoimageable Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb Additional Fab Capabilities: Blind Vias, Buried Vias, <b>Embedded Resistors</b> , Foil Lamination, Sequential Lamination Controlled Impedance: Differential, Single-Ended		

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<p>Specification: MIL-PRF-31032/1, MIL-PRF-31032/2  Qualification Letters: VQE-02-002780, VQE-03-002980, VQE-12-023661  Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant  Max. Panel Size: 18" x 24"  Max. Number of Layers: 28  Max. Board Thickness: .239"  Min. Hole Size: .007" Drilled Plated-Through Hole Before Plating  Aspect Ratio: 11:1 Through-Hole  Min. Conductor Width/Space: .004 "/.004"  Hole Preparation: Permanganate Desmear, Permanganate Etchback, Plasma Desmear, Plasma Etchback  Hole Wall Conductive Coating: Electroless Copper  Copper Plating: Direct Current Plate  Hole Fill / Via Plug: <b>Conductive, Non-Conductive</b>  Solder Resist: Dry Film, Liquid Photoimageable  Finish System: ENIG, HASL, Hot Oil Reflow of Plated Sn/Pb  Additional Fab Capabilities: Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination  Controlled Impedance: Differential, Single-Ended</p>		

The effective date of this qualification is December 15, 2010. Test report number 31032-3328-11 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.

5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this Office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. If you have any questions, please contact Mr. Jonathan Stone, (614) 692-3022 or [vqe.js@dla.mil](mailto:vqe.js@dla.mil).

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualification Division

Visit us on the web at [www.landandmaritime.dla.mil/offices/sourcing\\_and\\_qualification](http://www.landandmaritime.dla.mil/offices/sourcing_and_qualification)